



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-09-30
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
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Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TSC240A1IDT	3DO7*UBHM1BA	A	BO2A	2025-09-30
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	80	mg	Each	ECOPACK® 3
<b>Identity</b>	<b>Authority</b>			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
DSO	4.9x3.9	8	gull wing
Comment			
Comment	07 SO 08 .15 JEDEC		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
<b>Exemption Id.</b>	<b>Description</b>

QueryList : California Prop65 list, dated 3rd January 2025	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	true		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	false		
<b>Substance</b>	<b>amount in product (mg)</b>	<b>Application</b>	<b>ppm in product</b>

QueryList :Customer	Response
<b>QUERY</b>	<b>Response</b>

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
<b>QUERY</b>	<b>Response</b>			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
<b>Hazardous substance</b>				
<b>Lead (Pb)</b>	<b>Cadmium (Cd)</b>	<b>Mercury (Hg)</b>	<b>Hexavalent Chromium (Cr VI)</b>	<b>PBB &amp; PBDE</b>
0	0	0	0	0

QueryList : REACH-25th June 2025	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	<b>Gold, Tin,</b>

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	true
<b>All the adhesive impacted complies with GB 33372</b>	<b>true</b>

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
<b>QUERY</b>	<b>Response</b>
The product is containing fluorinated substance.	False
<b>Substance Name, CAS</b>	

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration :						Mfr Item Name	3DO7*UBHM1BA		80.0000		5999999.0	1000006.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.544	mg	supplier	die	Silicon(Si)	7440-21-3		2.387	mg	938286	29838
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.026	mg	10220	325
				supplier	metallisation	Copper(Cu)	7440-50-8		0.004	mg	1572	50
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	393	13
				supplier	Passivation	Silicon nitride(Si)	12033-89-5		0.006	mg	2358	75
				supplier	passivation	Silicon oxide	7631-86-9		0.068	mg	26730	850
				supplier	polymer coating	polyimide	proprietary		0.052	mg	20440	650
Leadframe	M-004 Copper and its alloys	30.513	mg	supplier	alloy	Copper(Cu)	7440-50-8		29.124	mg	954478	364050
				supplier	alloy	Iron(Fe)	7439-89-6		0.685	mg	22449	8563
				supplier	alloy	Iron phosphide	1310-43-6		0.041	mg	1344	513
				supplier	alloy	Zinc(Zn)	7440-66-6		0.036	mg	1180	450
				supplier	metallization	Silver(Ag)	7440-22-4		0.627	mg	20549	7838
Die attach	M-011 Other inorganic materials	0.343	mg	supplier	glue	Silver(Ag)	7440-22-4		0.302	mg	880466	3775
				supplier	glue	Isobornyl Metha	7534-94-3		0.017	mg	49563	213
				supplier	glue	Isobornyl acryla	5888-33-5		0.017	mg	49563	213
				supplier	glue	Methyl acrylate	87320-05-6		0.007	mg	20408	88
Bonding wires	M-008 Precious metals	0.130	mg	supplier	wire	Gold(Au)	7440-57-5		0.130	mg	1000000	1625
Encapsulation	M-011 Other inorganic materials	45.752	mg	supplier	mold compound	Silica vitreous	60676-86-0		32.758	mg	715991	409475
				supplier	mold compound	Silicon oxide	7631-86-9		6.863	mg	150004	85788
				supplier	mold compound	Biphenyl epoxy	85954-11-6		3.431	mg	74991	42888
				supplier	mold compound	Phenol resin	26834-02-6		2.288	mg	50009	28600
				supplier	mold compound	Carbon black	1333-86-4		0.229	mg	5005	2863
				supplier	mold compound	Bismuth compo	7440-69-9		0.183	mg	4000	2288
Connections coating	Solder	0.718	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		0.718	mg	1000000	8975